

ABSTRACT

The structure and method of a Ball-Grid Array or Land-Grid Array plastic integrated circuit (IC) device are described, which have gold bumps on the chip contact pads, spaced apart by less than 100 µm center to center, flipchip attached to a thin-film plastic substrate. An overmold package provides stability for solder ball attachment to outside parts (FIG. 1). An optional nonconductive polymer adhesive, used as a bump underfill, provides additional package rigidity.